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1. A transfer molding apparatus comprises:  
a top-half mold and a bottom-half mold for forming a cavity as a  
5 molding space for a package and a transfer pot as a loading space,  
communicating with said cavity, for resin to be injected into said cavity;  
a plunger for forcing the resin out of the transfer pot into said cavity;  
and  
pressure adjusting means for reducing the pressure in said cavity when  
10 a specified amount of resin has been injected into said cavity.
2. A transfer molding apparatus according to Claim 1, wherein said top-  
half mold and said bottom-half mold form a plurality of cavities interconnected,  
and wherein said pressure adjusting means reduces the pressure of the  
cavities every time a specified amount of resin is supplied into any one of a  
15 plurality of cavities.
3. A transfer molding apparatus according to Claim 1, wherein said  
pressure adjusting means includes position detecting means for detecting the  
position of said plunger when a specified amount of resin has been supplied  
into said cavity.
- 20 4. A transfer molding apparatus according to Claim 2, wherein said  
pressure adjusting means includes position detecting means for detecting the  
position of said plunger when a specified amount of resin has been supplied  
into said cavity.
5. A transfer molding apparatus according to Claim 1, wherein said  
25 pressure adjusting means includes time counting means for counting time  
from the start of movement of said plunger until a specified amount of said  
resin has been supplied into said cavity.

6. A transfer molding apparatus according to Claim 2, wherein said pressure adjusting means includes time counting means for counting time from the start of movement of said plunger until a specified amount of said resin has been supplied into said cavity.

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A method for manufacturing semiconductor devices comprising the steps of:

placing a semiconductor-element-mounted lead frame between a top-half mold and a bottom-half mold; and

reducing the pressure in a cavity formed by said top-half mold and said

10 bottom-half mold when a specified amount of resin has been supplied into said cavity.

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